

3.2x1.6mm PHOTOTRANSISTOR

Part Number: KP-3216P3C

Features

- 3.2mmx1.6mm SMT LED, 1.1mm thickness.
- Mechanically and spectrally matched to infrared emitting

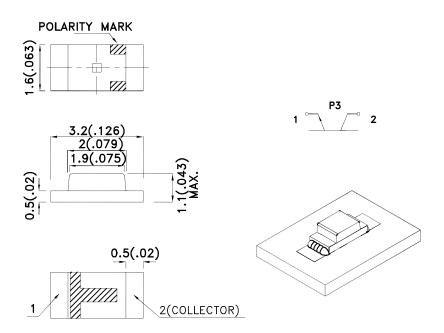
LED lamp.

- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

Made with NPN silicon phototransistor chips.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.2(0.0079") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice. 4.The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAA4436 APPROVED: WYNEC

REV NO: V.12 CHECKED: Allen Liu

DATE: SEP/04/2012 DRAWN: D.M.Su

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Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
VBR CEO	Collector-to-Emitter Breakdown Voltage	30			V	Ic=100uA Ee=0mW/c m²
VBR ECO	Emitter-to-Collector Breakdown Voltage	5			V	IE=100uA Ee=0mW/c m²
VCE (SAT)	Collector-to-Emitter Saturation Voltage			0.8	V	Ic=2mA Ee=20mW/c m³
I CEO	Collector Dark Current			100	nA	VcE=10V Ee=0mW/c m²
Tr	Rise Time (10% to 90%)		15		us	VcE = 5V Ic=1mA RL=1000Ω
TF	Fall Time (90% to 10%)		15		us	
I (ON)	On State Collector Current	0.2	0.4		mA	VcE = 5V Ee=1mW/c m ² λ=940nm
201/2	Angle of half sensitivity		120		deg	

Absolute Maximum Ratings at TA=25°C

Parameter	Max.Ratings			
Collector-to-Emitter Voltage	30V			
Emitter-to-Collector Voltage	5V			
Power Dissipation at (or below) 25°C Free Air Temperature	100mW			
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

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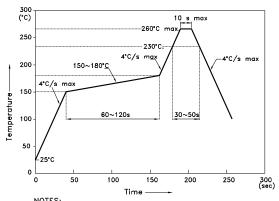
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

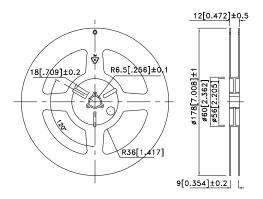
1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specifications (Units : mm)

4.0±0.1 ø1.5^{+0.1} 4.0±0.1 2.0±0.05 0.229±0.013 1.3±0.1 $8.0^{+0.3}_{-0.1}$ 3.5 ± 0.05

TAPE

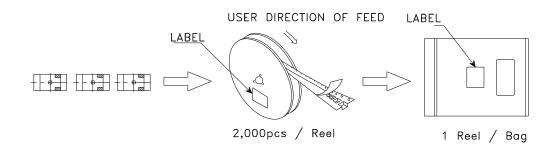
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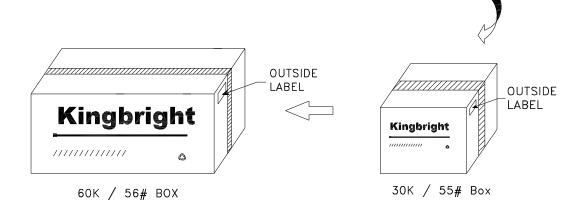
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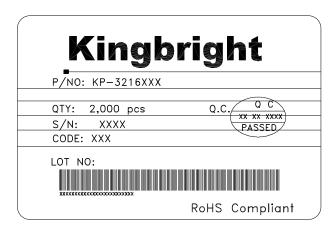
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PACKING & LABEL SPECIFICATIONS

KP-3216P3C







Detailed application notes are listed on our website. http://www.kingbright.com/application notes

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